

T-M5.3

Wire Bond Globe Top Package
For contact based application (Controller)

Short Product Overview

May 2010

Chip Card & Security

T-M5.3 Short Product Overview	Ref.: Chip_Card_Product_Overview_11/09
Revision History: Current Version 05.10	
Previous Releases:	
Page	

Important: Further information is confidential and on request. Please contact:
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Product name	T-M5.3
Picture	
Product description	Contact based module 8 contacts Epoxy Tape Wire Bond Glob Top
Typical Applications	Pay-TV
Pitch	14.25 mm
Dimensions	13 x 11.8 mm
Thickness	max. 580µm
Contact Surface	CIN+
Delivery form	Tape on Reel Reel diameter 330mm
ISO - reference	ISO/IEC 7810 SO/IEC 7816-1 ISO/IEC 10373-1 / -3
Derivatives	

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